

朝貴電子股份有限公司 CKM ELECTRONICS CO., LTD.

PRODUCT SPECIFICATION

CKM 2004 SERIES(Pb FREE)

2.0mm PITCH CONNECTOR

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| REVISION: | |
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| EVISION: | ECR/ECN | NFORMATION: | TITLE: 2.0MN | ITLE: 2.0MM PIN HEADER/BOX | | |
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| DOCUMENT NUMBER: | | CREATED/REVISED | CHECKED BY | APPROVED BY | | |
| SP-2004-002 | | Jimmy Wang | Lance Cheng | Ivan Su | | |
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1.0 SCOPE

This product specification covers performance, tests and quality requirements for **2004** Connector System When tests are performed on subject product line, procedures specified in Figure 1 shall be used. All inspections shall be performed using the applicable product drawing.

2.0 APPLICABLE DOCUMENTS

- 2.1. The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of the specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.
- 2.2. Applicable documents and specifications EIA-364 & UL-94 Flammability

3.0 REQUIREMENTS

3.1. Design and Construction

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing

3.2. Material

Materials used in the construction of this product shall be as specified on the applicable product drawing

- 3.3. Ratings
 - 1. Voltage Rating: 250V DC
 - 2. Current Rating: 1.0A (#26 AWG)
 - 3. Operating temperature: -40+105°C
- 3.4. Performance Requirements and Test Descriptions The product is designed to meet the electrical, mechanical and environmental performance requirements as specified in Figure 1. Unless otherwise specified, all tests are performed at ambient environmental conditions.
- 3.5. Test Requirements and Procedures Summary

| Test Description | Requirement | Procedure | | | |
|--|--|---|--|--|--|
| Initial examination of product. | Meets requirements of product drawing and Application. | Visual and dimensional (C of C) inspection per product drawing. (EIA-364-18) | | | |
| Final examination of product. Meets visual requirements. | | Visual inspection. (EIA-364-18) | | | |
| ELECTRICAL | | | | | |
| Low Level Contact Resistance (LLCR). | 20mΩ max. initial. 30mΩ max. final. | Subject specimens to 100mA Max. and 20mV Max. open circuit voltage. See Figure 3.(EIA-364-23) | | | |

| Insulation Resistance. | 1000MΩ Min (Initial) | 500V DC, 2 minute hold. Test between adjacent contacts. (EIA-364-21) |
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Temperature life.

Salt Spray

1 minute hold with no 800VAC at sea level. Test between adjacent Withstanding voltage. breakdown or flashover. contacts. (EIA-364-20, Condition I) 5.0mA max. leakage current. Stabilize at a single current level until 3 readings 30°C max. Temperature rise at 5 minute intervals are within 1°C. Temperature rise at specified current. (EIA-364-70, Method 1) **MECHANICAL** Measure force necessary to mate specimens with companion headers at a maximum rate of 12.7mm Mating force. 0.2kgf Max. per contact. per minute. (EIA-364-13) Measure force necessary to un mate specimens Un mating force. 0.01kgf Min. per contact. from companion headers at a maximum rate of 12.7mm per minute. (EIA-364-13) Manually mate and unmate specimens with Durability See Note. companion headers for 30 cycles at a max. rate of 500 cycles per hour. (EIA-364-9) Before dipping in tin 1.0kg Min. Determine crimp tensile at a rate of 25.4mm per Crimp tensile. After dipping in tin 0.5kg Min. minute. (EIA-364-8) Apply axial load at Max. rate of 25.4mm per minute **Pin Retention Force** 0.25kgf Min. until dislodged. (EIA-364-29) **ENVIRONMENTAL** 5 cycles at -40°C to +105°C. Thermal shock. See Note. (EIA-364-32, Test condition VIII) 40°C at 95% RH. for 96 hours. Humidity cycling. See Note. (EIA-364-31, Method III) Subject mated specimens to 105°C for 96 hours.

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EIA-364-26,

Duration : 24Hours

(EIA-364-17, Method A, Test Condition 4, Test Time Condition C)

Mated connector shall be placedon a salt spray

Salt Solution Density : 5±1% Temperature : 35±1°C

chamber on the following conditions

See Note.

See Note.



| Solder ability The contact solder tails show be covered by a continuou new solder coating for min 99 of affected area. | | Subject contacts to solderability testing, as specified solder transfer at 245±5°C for 3±0.5s. |
|---|---------------------------------|--|
| Soldering iron method | No damage | Apply solder iron in solder tail Temperature: 350±10°C, 3 sec. |
| Resistance to Wave Soldering Heat | No physical damage shall occur. | Subject product mounted on printed circuit board to solder bath at 260±5°C for 5s±0.5s. |
| | Figu | re 1 |

NOTE

Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Requalification Test Sequence shown in Figure2.

| Test or Examination1Initial examination of product1LLCR4.6 | 2 1 2.6 | 3 Test Sequ 1 | 4 ence (b) | 5 | 6 | |
|--|-----------------|---------------------|---------------|-------|-------------|----------|
| Initial examination of product 1 LLCR 4.6 | 1 2.6 | Test Sequ | ence (b) | † | | |
| Initial examination of product1LLCR4.6 | 1 2.6 | 1 | 1 | 1 | | |
| LLCR 4.6 | 2.6 | | 1 1 | 1 | 1 | |
| | | | | 2.4 | 2.6 | |
| Insulation resistance | 3.7 | 2.5 | | | 3.7 | |
| Withstanding voltage | 4.8 | 3.6 | | | 4.8 | |
| Temperature rise vs current | | | 2 | | | |
| Solder ability dip test | | | | | | |
| Durability 5 | | | | | | |
| Mating force 2 | | | | | | |
| Un mating force 3 | | | | | | |
| Crimp tensile | | | | | | |
| Contact retention | | | 3 | | | |
| Thermal shock | 5 | | | | | |
| Humidity cycling | | 4(c) | | | | |
| Temperature life | | | | | 5 | |
| Salt Spray | | | | 3 | | |
| Final examination of product 7 | 9 | 7 | 4 | 5 | 9 | |
| | Figure 2 | 2 | | | | |
| NOTE: | · | | | | | |
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Test Sequence



(a)See paragraph 4.1.A.

(b)Numbers indicate sequence in which tests are performed.

(c)Precondition specimens with 10 durability cycles.

4. QUALITY ASSURANCE PROVISIONS

- 4.1 Qualification Testing
 - 1. Specimen Selection

Specimens shall be prepared in accordance with applicable Instruction Sheets and shall be selected at random from current production. Test groups 1, 2, 3 and 5 shall each consist of a minimum of 5 specimens with a minimum of 30 data points. Test group 4 shall consist of a minimum of 5 specimens with a minimum of 30 header posts

2. Test Sequence

Qualification inspection shall be verified by testing specimens as specified in Figure 2.

4.2 Requalification Testing

If changes significantly affecting form, fit or function are made to the product or manufacturing process, product assurance shall coordinate requalification testing, consisting of all or part of the original testing sequence as determined by development/product, quality and reliability engineering.

4.3 Acceptance

Acceptance is based on verification that the product meets the requirements of Figure 1. Failures attributed to equipment, test setup or operator deficiencies shall not disqualify the product. If product failure occurs, corrective action shall be taken and specimens resubmitted for qualification. Testing to confirm corrective action is required before resubmittal.

4.4 Quality Conformance Inspection

The applicable quality inspection plan shall specify the sampling acceptable quality level to be used. Dimensional and functional requirements shall be in accordance with the applicable product drawing and this specification.

